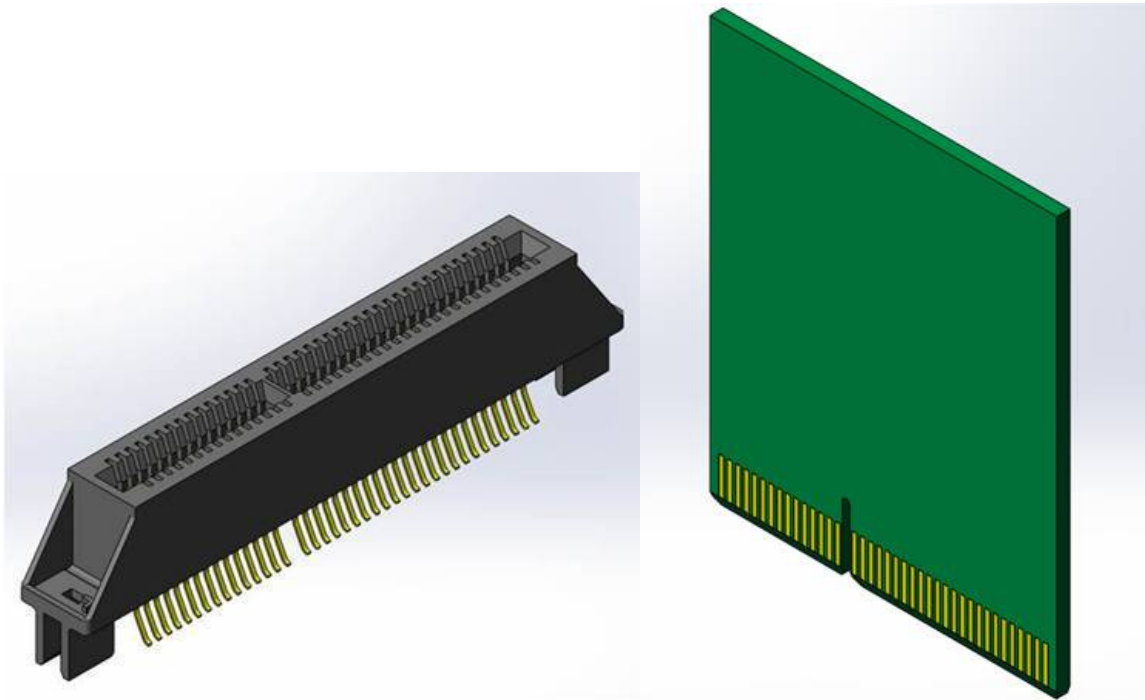




Project Number: Design Qualification Test Report		Tracking Code: 234665_Report_Rev_1	
Requested by: Catie Eichhorn		Date: 5/10/2013	Product Rev: Q
Part #: MEC1-140-02-L-D-EM2/Edge card			Tech: Kason He Eng: Vico Zhao
Part description: MEC1/ Edge card			Qty to test: 50
Test Start: 3/26/2012		Test Completed: 4/30/2013	



DESIGN QUALIFICATION TEST REPORT

MEC1/Edge card
MEC1-140-02-L-D-EM2/Edge card

Tracking Code: 234665_Report_Rev_1	Part #: MEC1-140-02-L-D-EM2/Edge card
Part description: MEC1/ Edge card	

REVISION HISTORY

DATA	REV.NUM.	DESCRIPTION	ENG
5/8/2013	1	Initial Issue	KH

Tracking Code: 234665_Report_Rev_1	Part #: MEC1-140-02-L-D-EM2/Edge card
Part description: MEC1/ Edge card	

CERTIFICATION

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to ISO 10012-1 and ANSI/NCSL 2540-1, as applicable.

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SCOPE

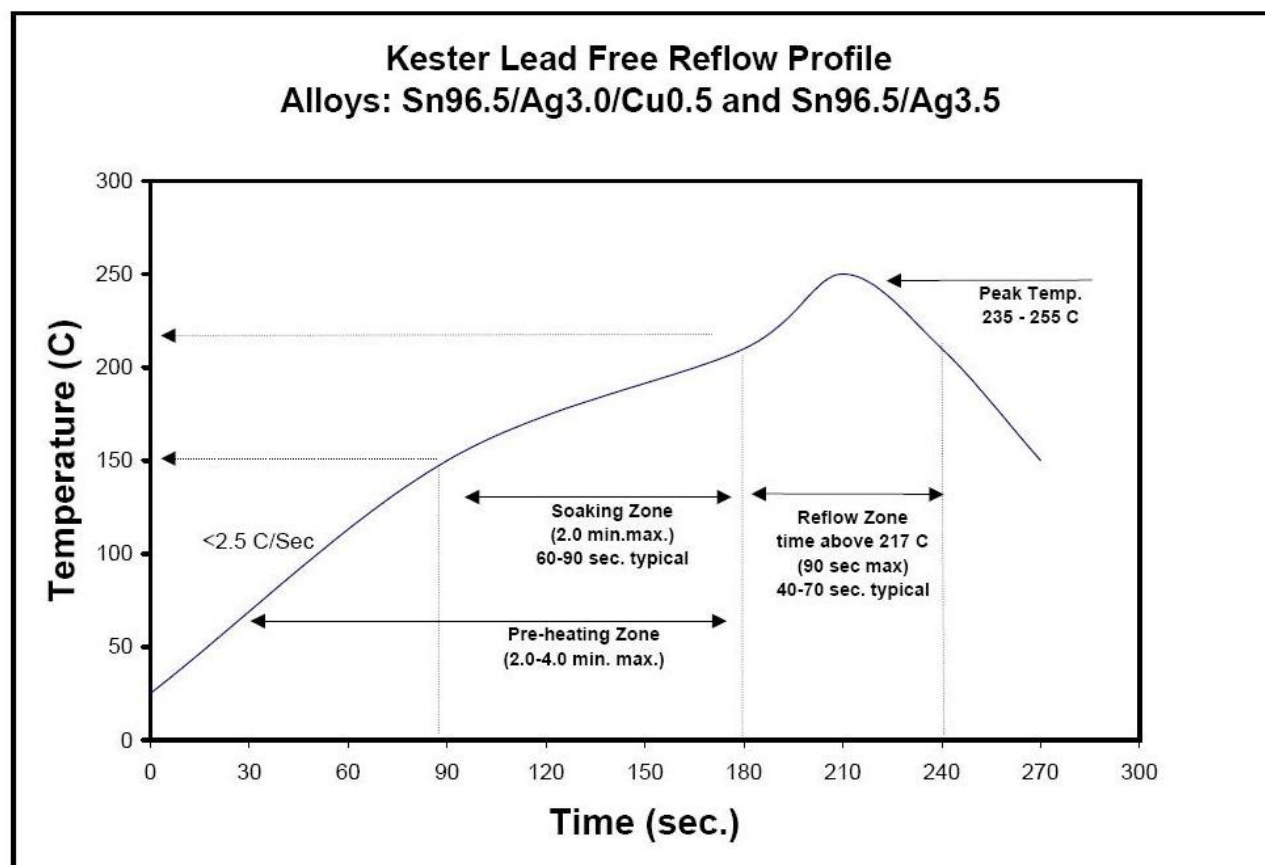
To perform the following tests: Design Qualification test. Please see test plan.

APPLICABLE DOCUMENTS

Standards: EIA Publication 364

TEST SAMPLES AND PREPARATION

- 1) All materials were manufactured in accordance with the applicable product specification.
- 2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
- 3) After soldering, the parts to be used for LLCR testing were cleaned according to TLWI-0001.
- 4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
- 5) The automated procedure is used with aqueous compatible soldering materials.
- 6) Parts not intended for testing LLCR are visually inspected and cleaned if necessary.
- 7) Any additional preparation will be noted in the individual test sequences.
- 8) Solder Information: Lead Free
- 9) Re-Flow Time/Temp: See accompanying profile.
- 10) Samtec Test PCBs used: PCB-104143-TST/PCB-104144-TST/ PCB-104145-TST

TYPICAL OVEN PROFILE (Soldering Parts to Test Boards)

FLOWCHARTS

Current Carrying Capacity - Double Row

TEST STEP	GROUP B1 3 Mated Assemblies 2 Contacts Powered	GROUP B2 3 Mated Assemblies 4 Contacts Powered	GROUP B3 3 Mated Assemblies 6 Contacts Powered	GROUP B4 3 Mated Assemblies 8 Contacts Powered	GROUP B5 3 Mated Assemblies All Contacts Powered
01	CCC	CCC	CCC	CCC	CCC

(TIN PLATING) - Tabulate calculated current at RT, 65°C, 75°C and 95°C
after derating 20% and based on 105°C

(GOLD PLATING) - Tabulate calculated current at RT, 85°C, 95°C and 115°C
after derating 20% and based on 125°C

CCC, Temp rise = EIA-364-70

Mechanical Shock / Vibration / LLCR

TEST STEP	GROUP 1 8 Assemblies (.056" Edge Card)	GROUP 2 8 Assemblies (.068" Edge Card)
01	LLCR-1	LLCR-1
02	Shock	Shock
03	Vibration	Vibration
04	LLCR-2	LLCR-2

Mechanical Shock = EIA 364-27 Half Sine,

100 g's, 6 milliSeconds (Condition "C") each axis

Vibration = EIA 364-28, Random Vibration

7.56 g RMS, Condition VB --- 2 hours/axis

LLCR = EIA-364-23, LLCR

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

Shock / Vibration / nanoSecond Event Detection

TEST STEP	GROUP A1 60 Points (0.056" Edge Card)
01	Event Detection, Shock
02	Event Detection, Vibration

Mechanical Shock = EIA 364-27 Half Sine,

100 g's, 6 milliSeconds (Condition "C") each axis

Vibration = EIA 364-28, Random Vibration

7.56 g RMS, Condition VB --- 2 hours/axis

Event detection requirement during Shock / Vibration is 50 nanoseconds minimum

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

MECHANICAL SHOCK (Specified Pulse):

- 1) Reference document: EIA-364-27, *Mechanical Shock Test Procedure for Electrical Connectors*
- 2) Test Condition C
- 3) Peak Value: 100 G
- 4) Duration: 6 Milliseconds
- 5) Wave Form: Half Sine
- 6) Velocity: 12.3 ft/s
- 7) Number of Shocks: 3 Shocks / Direction, 3 Axis (18 Total)

VIBRATION:

- 1) Reference document: EIA-364-28, *Vibration Test Procedure for Electrical Connectors*
- 2) Test Condition V, Letter B
- 3) Power Spectral Density: 0.04 G² / Hz
- 4) G 'RMS': 7.56
- 5) Frequency: 50 to 2000 Hz
- 6) Duration: 2.0 Hours per axis (3 axis total)

NANOSECOND-EVENT DETECTION:

- 1) Reference document: EIA-364-87, *Nanosecond-Event Detection for Electrical Connectors*
- 2) Prior to test, the samples were characterized to assure the low nanosecond event being monitored will trigger the detector.
- 3) After characterization it was determined the test samples could be monitored for 50 nanosecond events

ATTRIBUTE DEFINITIONS Continued

The following is a brief, simplified description of attributes

TEMPERATURE RISE (Current Carrying Capacity, CCC):

- 1) EIA-364-70, *Temperature Rise versus Current Test Procedure for Electrical Connectors and Sockets*.
- 2) When current passes through a contact, the temperature of the contact increases as a result of I^2R (resistive) heating.
- 3) The number of contacts being investigated plays a significant part in power dissipation and therefore temperature rise.
- 4) The size of the temperature probe can affect the measured temperature.
- 5) Copper traces on PC boards will contribute to temperature rise:
 - a. Self heating (resistive)
 - b. Reduction in heat sink capacity affecting the heated contacts
- 6) A de-rating curve, usually 20%, is calculated.
- 7) Calculated de-rated currents at three temperature points are reported:
 - a. Ambient
 - b. 80° C
 - c. 95° C
 - d. 115° C
- 8) Typically, neighboring contacts (in close proximity to maximize heat build up) are energized.
- 9) The thermocouple (or temperature measuring probe) will be positioned at a location to sense the maximum temperature in the vicinity of the heat generation area.
- 10) A computer program, *TR 803.exe*, ensures accurate stability for data acquisition.
- 11) Hook-up wire cross section is larger than the cross section of any connector leads/PC board traces, jumpers, etc.
- 12) Hook-up wire length is longer than the minimum specified in the referencing standard.

LLCR:

- 1) EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets*.
- 2) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 3) The following guidelines are used to categorize the changes in LLCR as a result from stressing
 - a. $\leq +5.0$ mOhms:----- Stable
 - b. $+5.1$ to $+10.0$ mOhms:----- Minor
 - c. $+10.1$ to $+15.0$ mOhms:----- Acceptable
 - d. $+15.1$ to $+50.0$ mOhms:----- Marginal
 - e. $+50.1$ to $+2000$ mOhms:----- Unstable
 - f. $>+2000$ mOhms:----- Open Failure

RESULTS

Temperature Rise, CCC at a 20% de-rating

- CCC for a 30°C Temperature Rise -----1.5A per contact with 2 adjacent contacts powered
- CCC for a 30°C Temperature Rise -----1.2A per contact with 4 adjacent contacts powered
- CCC for a 30°C Temperature Rise -----1.0A per contact with 6 adjacent contacts powered
- CCC for a 30°C Temperature Rise -----0.9A per contact with 8 adjacent contacts powered
- CCC for a 30°C Temperature Rise -----0.5A per contact with all adjacent contacts powered

LLCR Shock & Vibration (192 LLCR test points)

0.056 Edge card

- Initial ----- 33.83mOhms Max
- Shock & Vibration
 - <= +5.0 mOhms ----- 190 Points ----- Stable
 - +5.1 to +10.0 mOhms -----2 Points ----- Minor
 - +10.1 to +15.0 mOhms -----0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms -----0 Points ----- Marginal
 - +50.1 to +2000 mOhms -----0 Points ----- Unstable
 - >+2000 mOhms -----0 Points ----- Open Failure

0.068 Edge card

- Initial ----- 31.09mOhms Max
- Shock & Vibration
 - <= +5.0 mOhms ----- 192 Points ----- Stable
 - +5.1 to +10.0 mOhms -----0 Points ----- Minor
 - +10.1 to +15.0 mOhms -----0 Points ----- Acceptable
 - +15.1 to +50.0 mOhms -----0 Points ----- Marginal
 - +50.1 to +2000 mOhms -----0 Points ----- Unstable
 - >+2000 mOhms -----0 Points ----- Open Failure

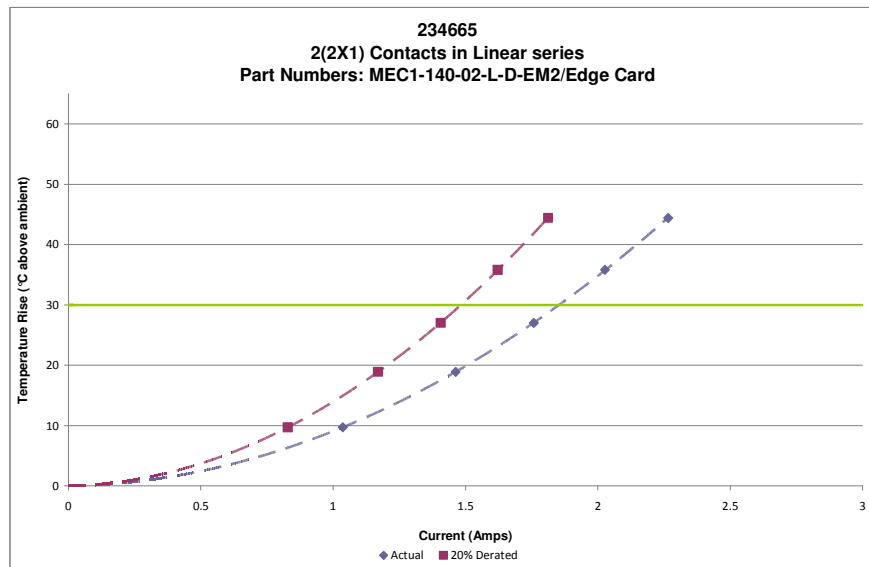
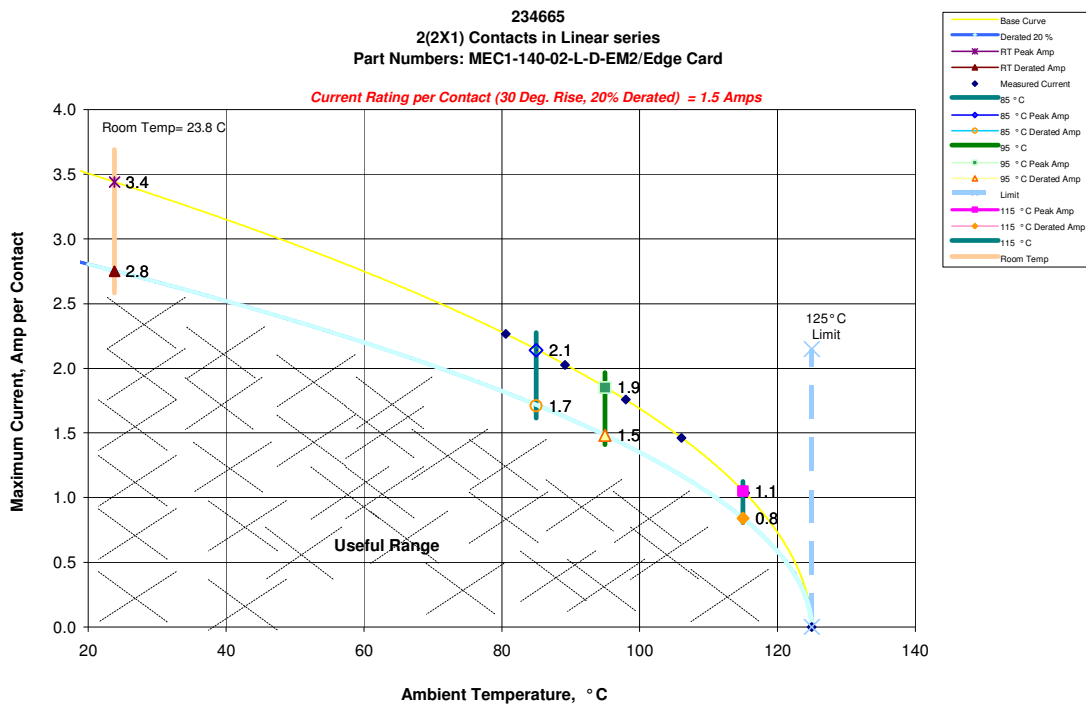
Mechanical Shock & Random Vibration:

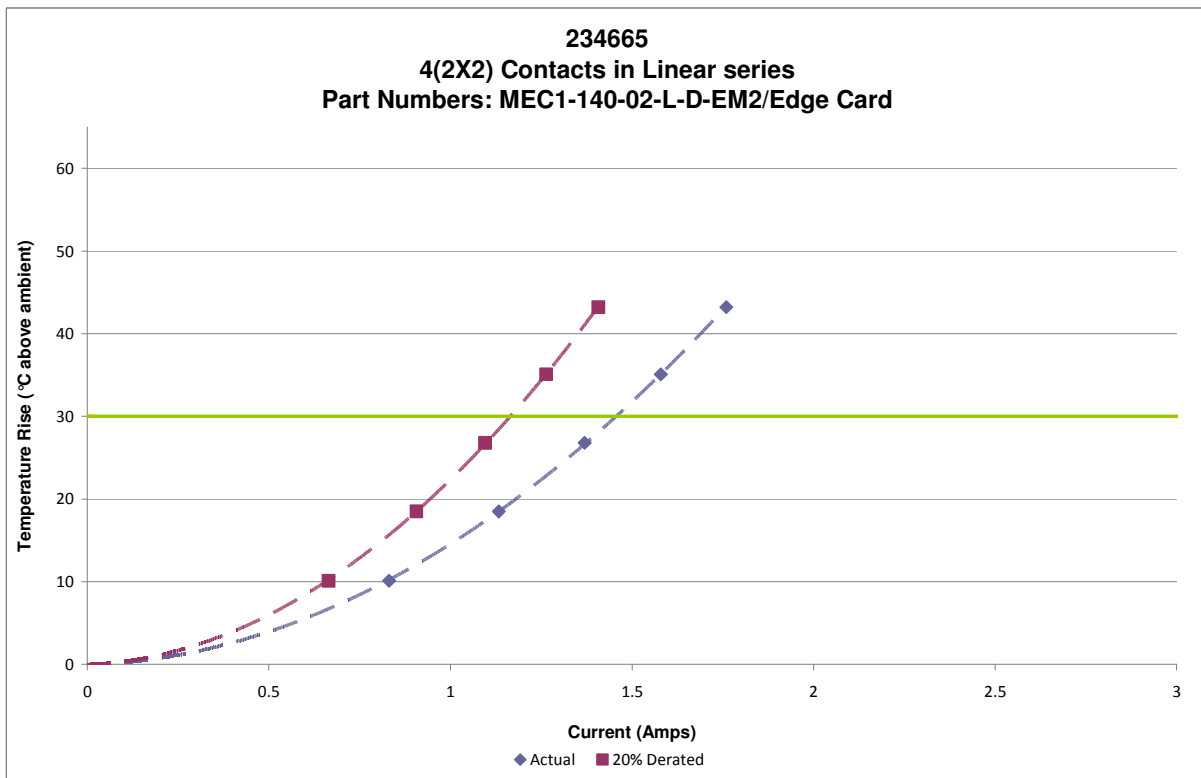
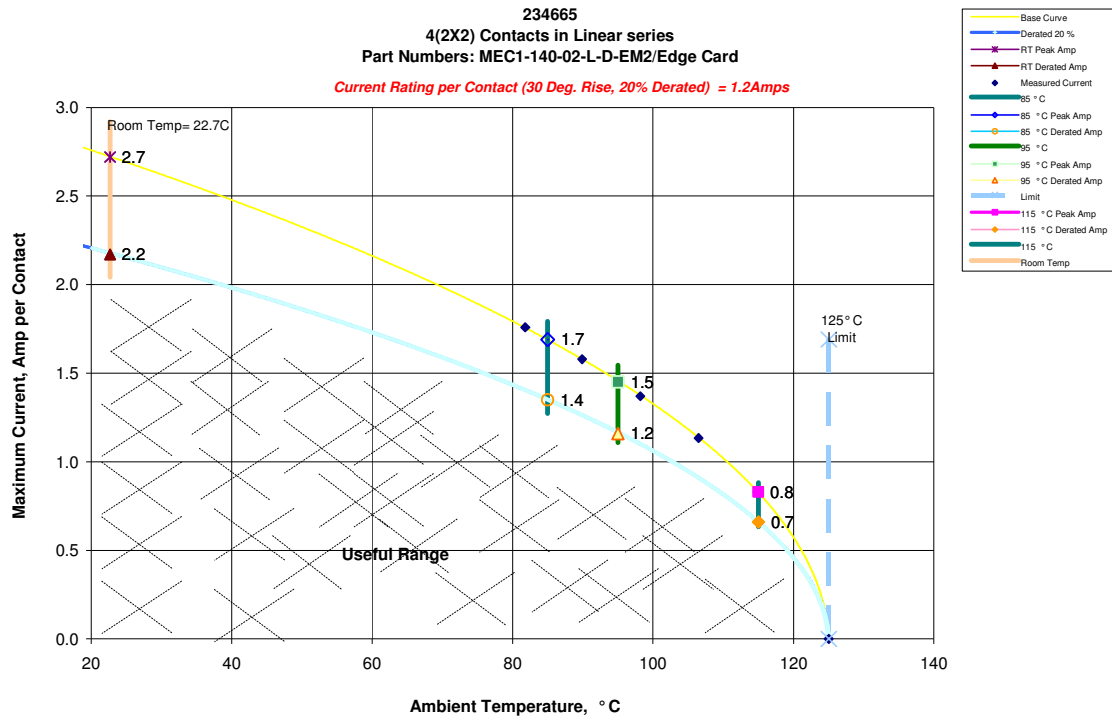
- Shock
 - No Damage----- Pass
 - 50 Nanoseconds----- Pass
- Vibration
 - No Damage----- Pass
 - 50 Nanoseconds----- Pass

DATA SUMMARIES

TEMPERATURE RISE (Current Carrying Capacity, CCC):

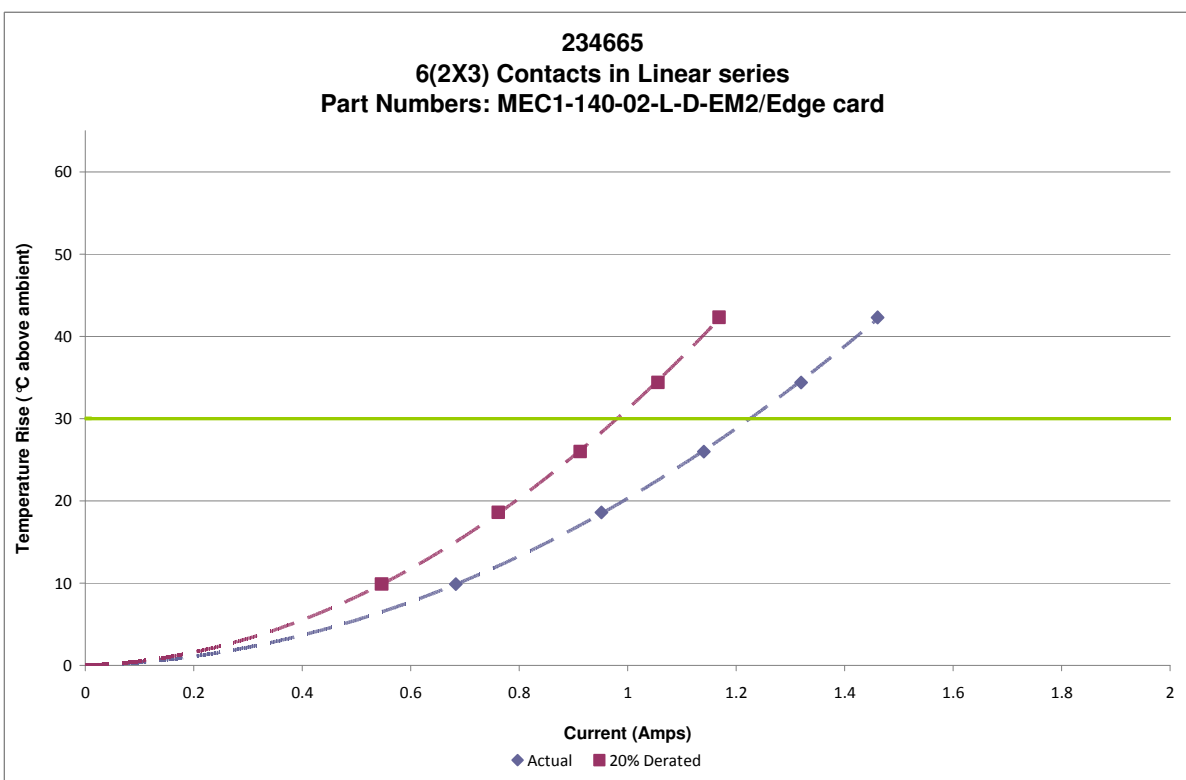
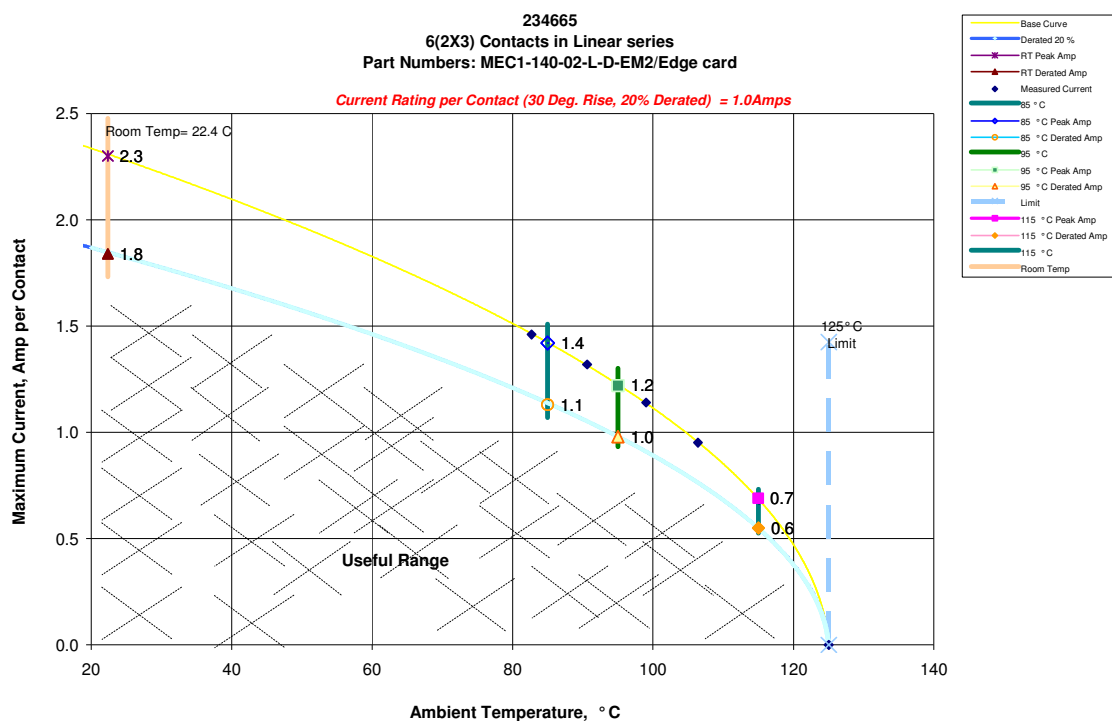
- 1) High quality thermocouples whose temperature slopes track one another were used for temperature monitoring.
- 2) The thermocouples were placed at a location to sense the maximum temperature generated during testing.
- 3) Temperature readings recorded are those for which three successive readings, 15 minutes apart, differ less than 1° C (computer controlled data acquisition).
- 4) Adjacent contacts were powered:
 - a. Linear configuration with 2 adjacent conductors/contacts powered



DATA SUMMARIES Continued**b. Linear configuration with 4 adjacent conductors/contacts powered**

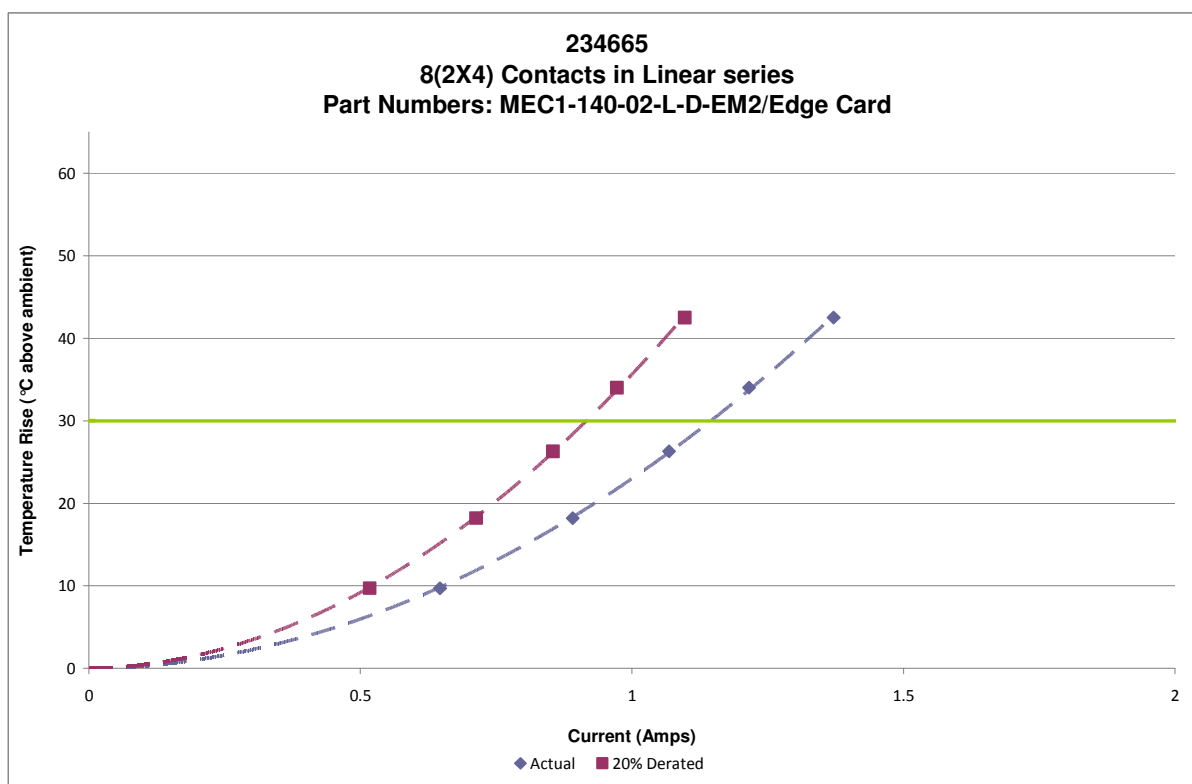
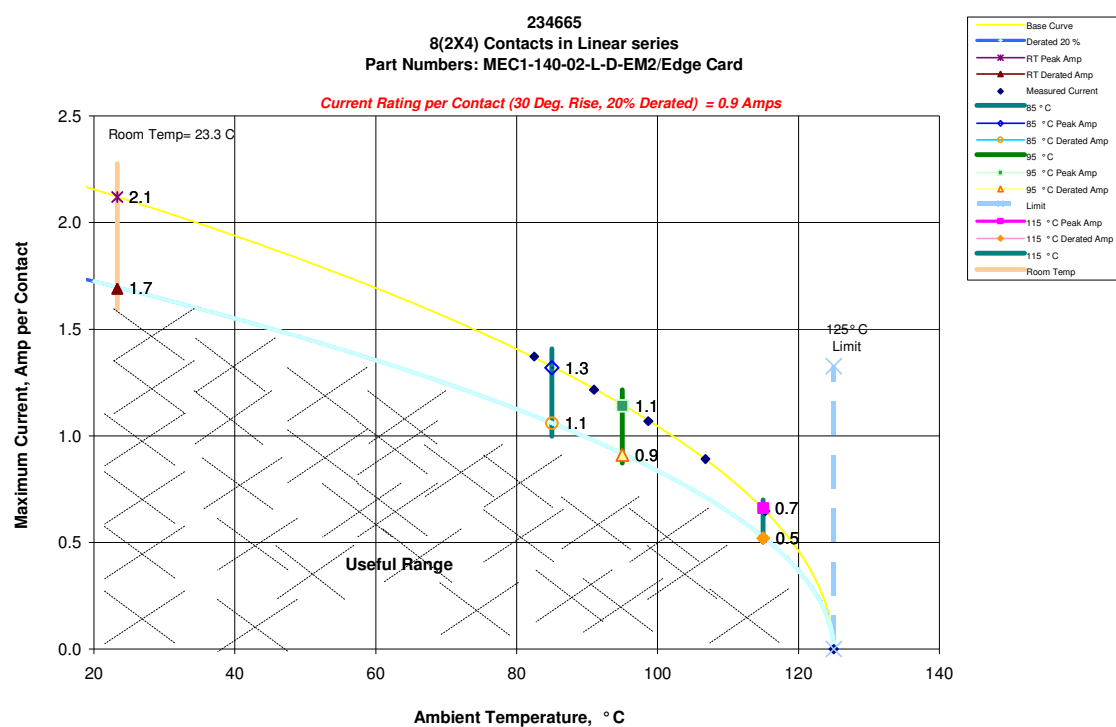
DATA SUMMARIES Continued

c. Linear configuration with 6 adjacent conductors/contacts powered



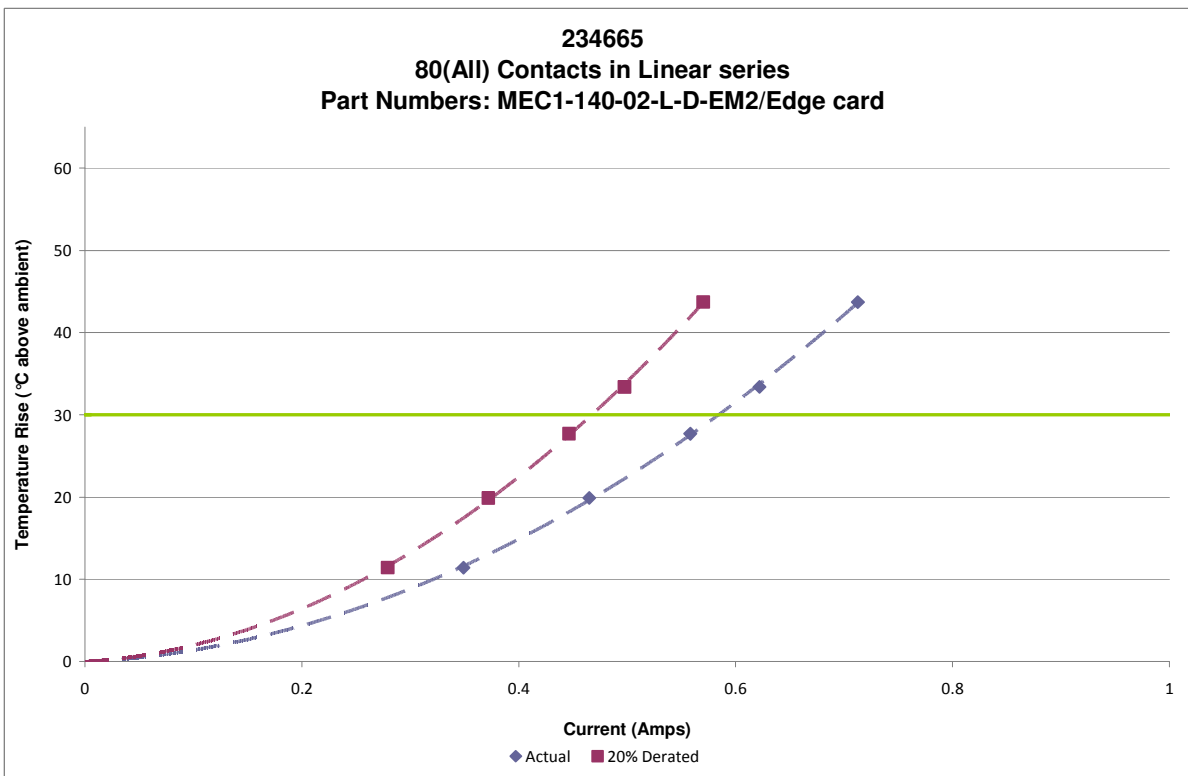
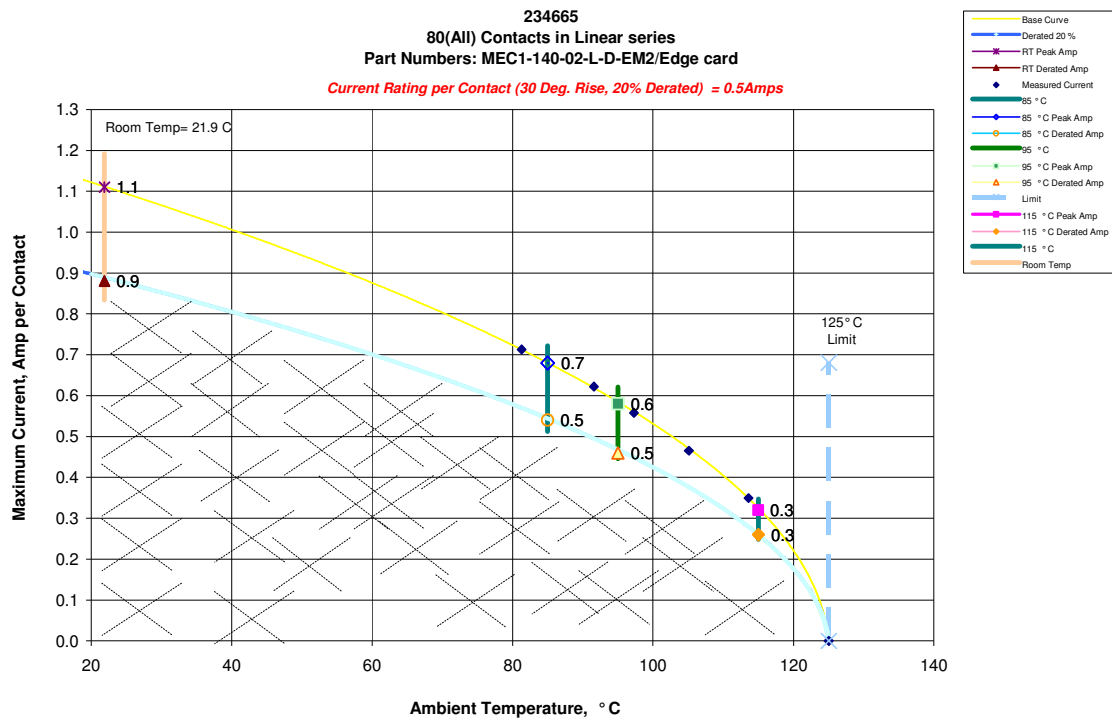
DATA SUMMARIES Continued

d. Linear configuration with 8 adjacent conductors/contacts powered



DATA SUMMARIES Continued

e. Linear configuration with all adjacent conductors/contacts powered



DATA SUMMARIES Continued**LLCR Shock & Vibration:**

- 1). A total of 192 points were measured.
- 2). EIA-364-23, *Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets*.
- 3). The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. $\leq +5.0$ mOhms: ----- Stable
 - b. $+5.1$ to $+10.0$ mOhms: ----- Minor
 - c. $+10.1$ to $+15.0$ mOhms: ----- Acceptable
 - d. $+15.1$ to $+50.0$ mOhms: ----- Marginal
 - e. $+50.1$ to $+2000$ mOhms: ----- Unstable
 - f. $>+2000$ mOhms: ----- Open Failure

LLCR Measurement Summaries by Pin Type		
Date	2013-3-26	2013-4-30
Room Temp (Deg C)	22	23
Rel Humidity (%)	34	40
Technician	Aaron McKim	Aaron McKim
mOhm values	Actual Initial	Delta Shock-Vib
.056 Edge Card	Pin Type 1: Signal	
Average	30.74	0.94
St. Dev.	1.13	0.97
Min	26.52	0.01
Max	33.83	6.27
Summary Count	192	192
Total Count	192	192

LLCR Delta Count by Category						
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	≤ 5	$>5 \text{ \& } \leq 10$	$>10 \text{ \& } \leq 15$	$>15 \text{ \& } \leq 50$	$>50 \text{ \& } \leq 1000$	>1000
Shock-Vib	190	2	0	0	0	0

Nanosecond Event Detection:

Shock and Vibration Event Detection Summary	
Contacts tested	60
Test Condition	C, 100g's, 6ms, Half-Sine
Shock Events	0
Test Condition	V-B, 7.56 rms g
Vibration Events	0
Total Events	0

Tracking Code: 234665_Report_Rev_1	Part #: MEC1-140-02-L-D-EM2/Edge card
Part description: MEC1/ Edge card	

DATA SUMMARIES Continued

LLCR Measurement Summaries by Pin Type	
Date	2013-3-26 2013-4-25
Room Temp (Deg C)	23 24
Rel Humidity (%)	31 30
Technician	Aaron McKim Aaron McKim
mOhm values	Actual Delta
	Initial Shock-Vib
.068 Edge Card	Pin Type 1: Signal
Average	28.21 0.31
St. Dev.	1.78 0.30
Min	25.13 0.00
Max	31.09 1.55
Summary Count	192 192
Total Count	192 192

LLCR Delta Count by Category						
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
Shock-Vib	192	0	0	0	0	0

EQUIPMENT AND CALIBRATION SCHEDULES**Equipment #:** HZ-MO-01**Description:** Micro-ohmmeter**Manufacturer:** Keithley**Model:** 2700**Serial #:** 1199807**Accuracy:** Last Cal: 4/27/2012, Next Cal: 4/26/2013**Equipment #:** HZ-PS-01**Description:** Power Supply**Manufacturer:** Agilent**Model:** 6031A**Serial #:** MY41000982**Accuracy:** Last Cal: 4/27/2012, Next Cal: 4/26/2013**Equipment #:** HZ-MO-05**Description:** Micro-ohmmeter**Manufacturer:** Keithley**Model:** 3706**Serial #:** 1285188**Accuracy:** Last Cal: 11/15/2012, Next Cal: 11/14/2013**Equipment #:** SVC-01**Description:** Shock & Vibration Table**Manufacturer:** Data Physics**Model:** LE-DSA-10-20K**Serial #:** 10037**Accuracy:** See Manual

... Last Cal: 11/31/2012, Next Cal: 11/31/2013

Equipment #: ACLM-01**Description:** Accelerometer**Manufacturer:** PCB Piezotronics**Model:** 352C03**Serial #:** 115819**Accuracy:** See Manual

... Last Cal: 07/09/2012, Next Cal: 07/09/2013

Equipment #: ED-03**Description:** Event Detector**Manufacturer:** Analysis Tech**Model:** 32EHD**Serial #:** 1100604**Accuracy:** See Manual

... Last Cal: 06/04/2012, Next Cal: 06/04/2013